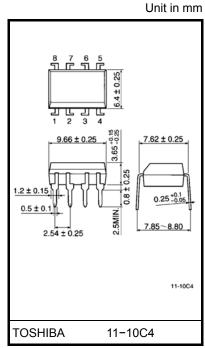
TOSHIBA Photocoupler GaAłAs Ired & Photo IC

6N135, 6N136

Digital Logic Isolation. Line Receiver. Power Supply Control Switching Power Supply Transistor Inverter

The TOSHIBA 6N135 and 6N136 consists of a high emitting diode and a one chip photo diode-transistor. Each unit is 8-lead DIP package.

- Isolation voltage: 2500V_{rms} (min.)
- High speed: t_{pHL} , $t_{pLH} = 0.5 \mu s$ (typ.) ($R_L = 1.9 k\Omega$)
- TTL compatible
- If base pin is open, output signal will be noisy by environmental condition. For this base, TLP550 is suitable
- UL recognized: UL1577, file no. E67349

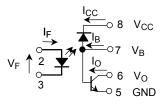


Weight: 0.54 g (typ.)

Pin Configurations



- 1 : N.C. 2 : ANODE
- 3 : CATHODE
- 4 : N.C.
- 5 : EMITTER
- 6 : COLLECTOR 7 : BASE, ANODE
- 8 : CATHODE



Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit	
LED	Forward current	(Note 1)	١ _F	25	mA
	Pulse forward current	(Note 2)	I _{FP}	50	mA
	Total pulse forward current	(Note 3)	I _{FPT}	1	A
	Reverse voltage	V _R	5	V	
	Diode power dissipation	(Note 4)	PD	45	mW
Detector	Output current		Ι _Ο	8	mA
	Peak output current	I _{OP}	16	mA	
	Emitter-base reverse voltage (p	V _{EB}	5	V	
	Supply voltage	V _{CC}	-0.5~15	V	
	Output voltage		V _O	-0.5~15	V
	Base current (pin 7)		Ι _Β	5	mA
	Output power dissipation	(Note 5)	Po	100	mW
Opera	Operating temperature range			-55~100	°C
Storage temperature range			T _{stg}	-55~125	°C
Lead solder temperature (10s) (Note 6)			T _{sol}	260	°C
Isolation voltage (Note 7)		BVS	2500	V _{rms}	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- (Note 1) Derate 0.8mA above 70°C.
- (Note 2) 50% duty cycle, 1ms pulse width. Derate 1.6mA / °C above 70°C.
- (Note 3) Pulse width 1 μ s, 300pps.
- (Note 4) Derate 0.9mW / °C above 70°C.
- (Note 5) Derate 2mW / °C above 70°C.
- (Note 6) Soldering portion of lead: Up to 2mm from the body of the device.
- (Note 7) R.H. \leq 60%, AC / 1min.

Electrical Characteristics Over Recommended Temperature (Ta = 0°C~70°C unless otherwise noted)

Characteristic		Symbol	Test Condition	Min.	(**)Typ.	Max.	Unit
	6N135	CTR	$I_F = 16mA, V_O = 0.4V$ $V_{CC} = 4.5V, Ta = 25^{\circ}C$ (Note 8)	7	18	_	%
Current transfer	6N136	UIK		19	24	_	%
ratio	6N135	CTR	I _F = 16mA, V _O = 0.5V	5	13		%
	6N136	UIK	V _{CC} = 4.5V (Note 1)	15	21		%
Logic low output	6N135	Vol	I _F = 16mA, I _O = 1.1mA V _{CC} = 4.5V	_	0.1	0.4	V
voltage	6N136	۷OL	I _F = 16mA, I _O = 2.4mA V _{CC} = 4.5V	—	0.1	0.4	V
Logic high output current		lou	I _F = 0mA, V _O = V _{CC} = 5.5V Ta = 25°C	_	3	500	nA
		IOH	$I_F = 0mA$, $V_O = V_{CC} = 15V$ Ta = 25°C	_	0.1	1	μA
		I _{ОН}	I _F = 0 mA, V _O = V _{CC} = 15V	—	—	50	μA
Logic low supply current		ICCL	I_F = 16mA, V _O = open V _{CC} = 15V	_	40		μA
Logic high supply current		ICCH	$I_F = 0mA$, $V_O = open$ $V_{CC} = 15V$, Ta = 25°C	_	0.01	1	μA
		ICCH	$I_F = 0mA$, $V_O = open$ $V_{CC} = 15V$	_	_	2	μA
Input forward voltage	Input forward voltage		I _F = 16mA, Ta = 25°C	_	1.65	1.7	V
Temperature coefficient of forward voltage		ΔV _F / ΔTa	I _F = 16mA	_	-1.9		mV / °C
Input reverse breakdown voltage		BV _R	I _R = 10μΑ, Ta = 25°C	5	_		V
Input capacitance		C _{IN}	f = 1MHz, V _F = 0	_	60		pF
Resistance (input-output)		R _{I-O}	V _{I−O} = 500V (Note 9) R.H. ≤ 60%	_	10 ¹²	_	Ω
Capacitance (input-output)		C _{I-O}	f = 1MHz (Note 9)	_	0.6	—	pF
Transistor DC current gain		h _{FE}	V _O = 5V, I _O = 3mA	_	80	_	—

(**) All typicals at Ta = 25°C

Switching Specifications (unless otherwise specified. Ta = 25°C, V_{CC} = 5V, I_F = 16mA)

Characteristic		Symbol	Test Circuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay	6N135	t _{pHL}	1	$R_L = 4.1 k\Omega$	_	0.2	1.5	μs
time to logic low at output	6N136			R _L = 1.9kΩ	_	0.2	0.8	μs
Propagation delay	6N135	t _{pLH}	1	R _L = 4.1kΩ	—	1.0	1.5	μs
time to logic high at output	6N136			R _L = 1.9kΩ	—	0.5	0.8	μs
Common mode transient immunity	6N135	- CM _H	2	$I_{F} = 0mA$ $V_{CM} = 10V_{p-p}$ $R_{L} = 4.1k\Omega$	_	1000	-	V / µs
at logic high level output (Note 10)	6N136			$I_{F} = 0mA$ $V_{CM} = 10V_{p-p}$ $R_{L} = 1.9k\Omega$	_	1000	_	V / µs
Common mode transient immunity	6N135	CML	2	$V_{CM} = 10V_{p-p}$ $R_L = 4.1k\Omega$ $I_F = 16mA$	_	-1000	_	V / µs
at logic low level output (Note 10)	6N136			$V_{CM} = 10V_{p-p}$ R _L = 1.9k Ω I _F = 16mA	_	-1000	_	V / µs
Bandwidth (Note 11)		BW	_	R _L = 100Ω	—	2	_	MHz

(Note 8) DC current transfer ratio is defined as the ratio of output collector current, I_O, to the forward LED input current, I_F, times 100%.

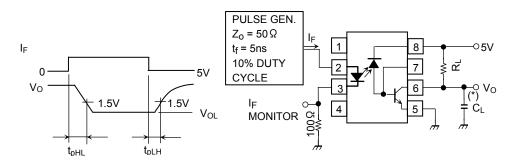
(Note 9) Device considered a two-terminal device: Pins 1, 2, 3, and 4 shorted together and pins 5, 6, 7 and 8 shorted together.

the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8V$).

(Note 11) The frequency at which the AC output voltage is 3dB below the low frequency asymptote.

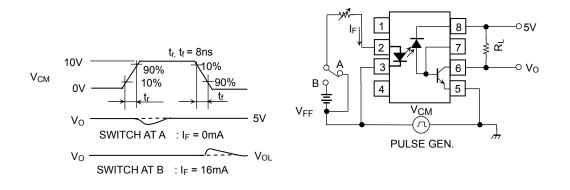
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Test Circuit 1.

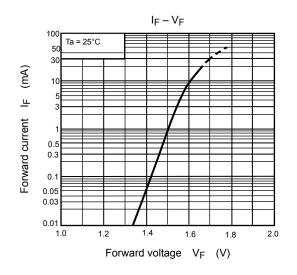


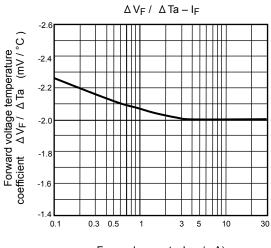
(*) C_L is approximately 15_PF which includes probe and stray wiring capacitance.

Test Circuit 2.

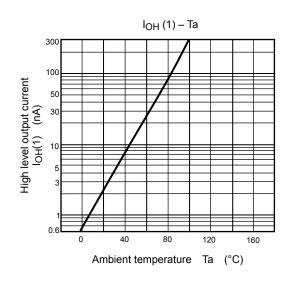


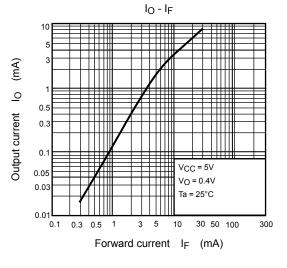
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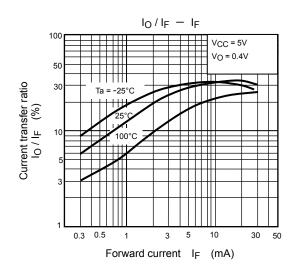


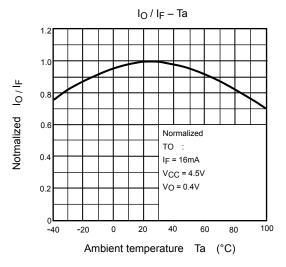


Forward current IF (mA)

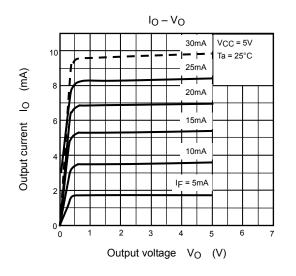


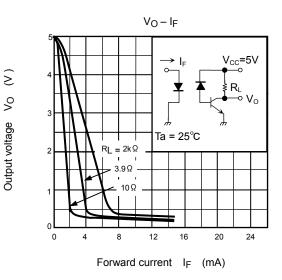


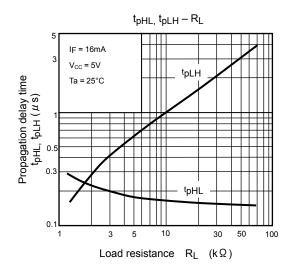




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